

10/100 BASE TRANSFORMERS

MODEL NO. : HA-003-1

FEATURES:

RoHS Compliant

Designed to meet IR requirement

RoHS peak solder rating 260°C / 3~5 Sec

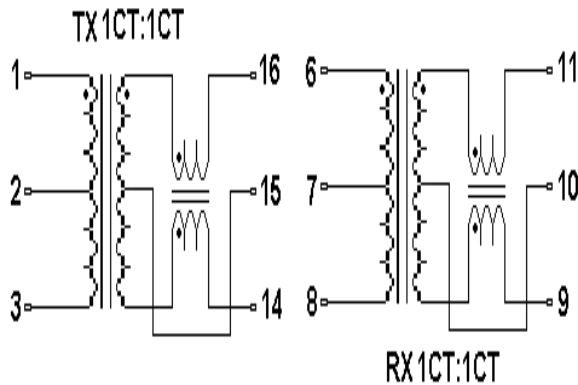
Specifications @ 25°C

Operating temp. : -40°C TO +85°C

OCL : 350uH Min @100Khz , 100mV 8mA

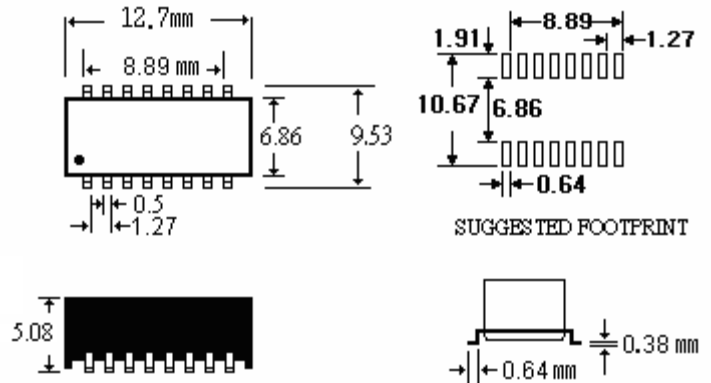
Part Number	Turns Ratio (±5%)		Insertion Loss (dB MAX)	Return Loss (dB MIN)			Common Mode Rejection (dB MIN.)			Cross Talk (dB MIN)		HIPOT (VAC)
	TX	RX		1~60 MHz	60~100 MHz	30 MHz	50 MHz	100 MHz	1~60 MHz	60~100 MHz		
HA-003-1	TX	RX	0.1~125 MHz	1~60 MHz	60~100 MHz	30 MHz	50 MHz	100 MHz	1~60 MHz	60~100 MHz	1500	
	1CT:1CT	1CT:1CT	-1.1	-16 ~ -14	-14 ~ -10	-42	-37	-33	-40	-38		

SCHEMATICS:

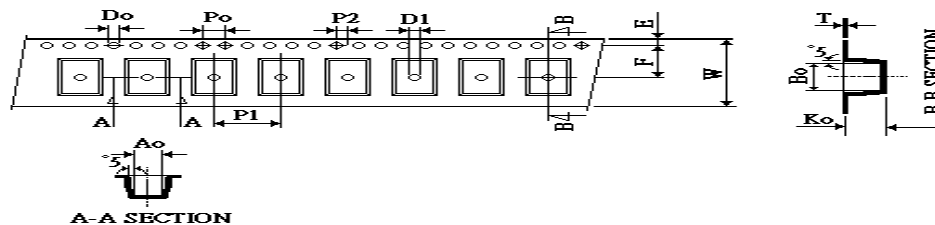


DIMENSION: mm

TOLERANCE: ±0.25



PACKING



DIMENSION	W	P1	PO	E	F	AO	BO	Aot
SPEC.	24.0	16.0	4.0	1.75	11.5	10.0	13.2	0.08
	+/- 0.30	0.10	0.10	0.10	0.10	0.10	0.10	(MIN)
DIMENSION	KO	P2	Do	D1	10Po	T	K1	Bot
SPEC.	6.80	2.0	1.55	1.5	40.0	0.40	6.15	0.08
	+/- 0.10	0.10	0.05	(MIN)	0.20	0.10	0.10	(MIN)

Tape & reel.....:600/reel
Tube.....:39/tub

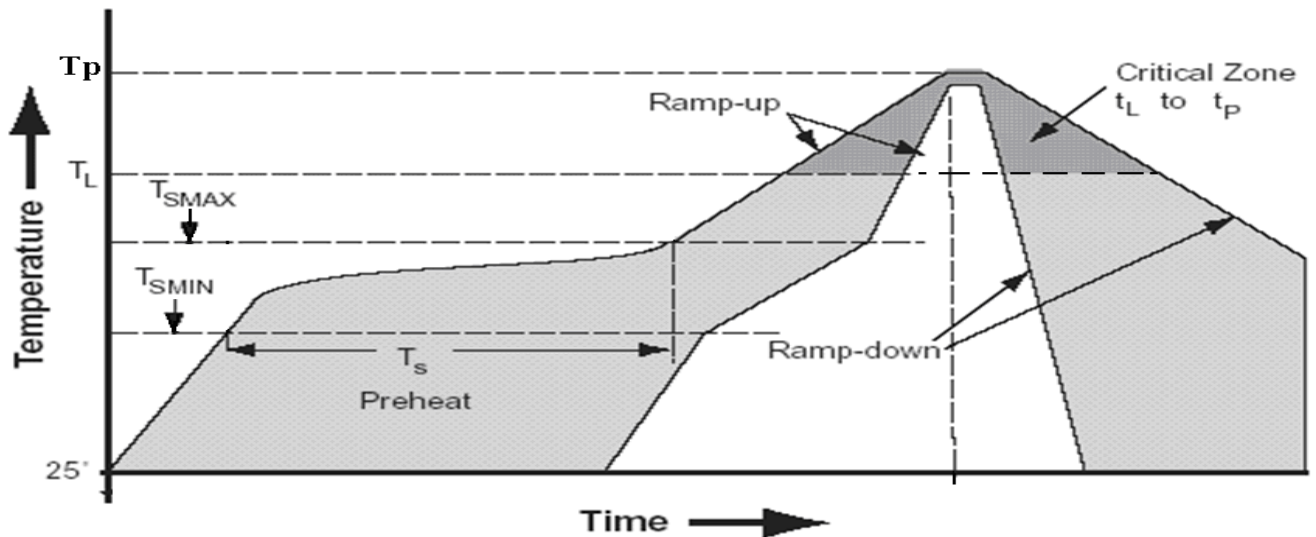
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Solder Reflow profile for Lead-Free packages.
Package Peak Reflow Temperatures

Classification Reflow Profiles

Profile Feature	Lead-Free Assembly	
Average ramp-up rate(T_L to T_P)	3°C / Second Max.	
Preheat Temperature Min.(T_s min.) Temperature Max.(T_s max.) Time (min to max) (T_s)	150 °C 200 °C 60-180 sec	
T_s max. to T_L Ramp-up Rate	3°C / Second Max.	
Time maintained above Temperature (T_L) Time (t_L)	217 °C 60-150 sec	
Peak Tempure (T_p) Time within 5 °C of actual peak Temp.	260 +0 / -5 °C 3 to 5 Sec	250 +0 / -5 °C 20 to 40 Sec
Ramp-down	6°C / Second Max.	
Time 25 °C to Peak Temperature	8 minutees Max.	

Profile



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1. Tape & Reel : 600pcs / Reel , 3000pcs / Carton
2. Dry Pack : 1pcs
Product Description:(5g Silica Gel Desiccant)
PH: 4-8
Package Materials: Paper(Length 6.5±1cm , Width 5±1cm)
3. Reel Packed By Vacuum
4. Seal Per JEDEC

